



HDBNC-J-P-GN-ST-EM1



HDBNC-J-P-GN-ST-BH1



HDBNC-J-P-GN-RA-BH1



HDBNC-J-P-GN-ST-TH1

HDBNC SERIES

75 Ω HIGH DENSITY BNC JACKS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDBNC-TH, www.samtec.com?HDBNC-BH1 or www.samtec.com?HDBNC-EM

Shell Material:

Au plated Brass

Contact Material:

Copper Alloy

Insulator Material:

PTFE

Impedance:

75 Ω $\pm$ 2 Ω

Frequency Range:

-EM & -TH: 0-12 GHz

-RA: 0-6 GHz

V.S.W.R:

1.45 max

(with optimized launch design)

Working Voltage:

330 Vrms max

Dielectric Withstanding:

1500 Vrms min

Contact Resistance:

Center Contact: 1.5m Ω max

Outer Contact: 0.4m Ω max

Operating Temperature:

-65 °C to +125 °C

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

Mates with:

RFB6T, RFB8T, RFA6T

4X THE PANEL DENSITY



Patented design
and bayonet latch

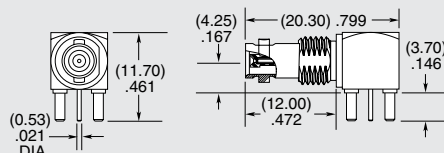
20% reduction in
weight of traditional
BNCs

Extended
performance
of 12G for
high density
-EM & -TH
terminations

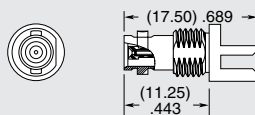
EXTRACTION TOOL

- Hand tool for quickly installing/uninstalling HDBNC Series.
Part Number:
CAT-EX-HDBNC-01
Contact Samtec.

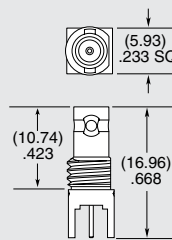
HDBNC	GENDER	TYPE	PLATING	ORIENTATION	TERMINATION
-J = Jack		-P = PCB Mount	-GN = 10 μ " (0.25 μ m) Gold contact, 100 μ " (2.54 μ m) Nickel shell	-ST = Straight -RA = Right Angle	-BH1 = Through-hole -BH2 = Through-hole (2.36 mm) .093 Board (-RA only) -EM1 = Edge Mount (-ST only) -TH1 = Through-hole (-ST only)



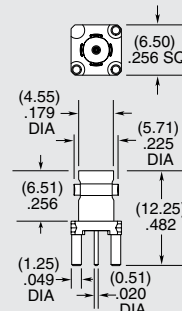
HDBNC-RA



HDBNC-EM1



HDBNC-BH1



HDBNC-TH1

Notes: Compatible with Amphenol's HD-BNC™

Designed to meet SMPTE 424M 12G-SDI specifications.